

AMENDMENTS

In the Specification

Please amend the paragraph on page 8, beginning on line 13 as follows:

FIGURE 2B illustrates various object classes 210, 215, 220, 225, 230, 235, 240, 245, 260, [260], 265, 270, 275 that a SALSA agent 200m invokes, in at least one embodiment, in order to control the introduction of new lots into the factory so as to avoid overburdening "bottleneck" manufacturing machines, while at the same time avoiding idle time ("starvation") at the bottleneck machines. A SALSA agent 200m is particularly useful in the context of semiconductor fabrication, because some features of wafer fabrication are not found in most other job shops. The photolithography process of wafer production requires the exposure of each of a multiple layers of photoresistive material through a mask. Because each layer of the wafer must be so exposed in the photolithography process, each lot of wafers repeatedly visits the photolithography workstation before it is completed. Since this equipment is very expensive, it is not overly abundant in the fab, and is therefore likely to be a bottleneck station. Thus, the special feature of wafer fabrication workflow that makes a SALSA agent 200m particularly useful is the repeated entry at a bottleneck workstation. A SALSA agent 200m focuses on the queue of work approaching the bottleneck workstation because such queue will on average be the biggest queue in the factory. A goal of at least one embodiment of a SALSA agent 200m is to allow high utilization rates of bottleneck machines while maintaining low levels of WIP.